Zener Diodes Panasonic

MALS068X

Silicon planar type

For constant voltage and surge absorption circuits

■ Features

- Bi-directional and high electrostatic discharge ESD
- Small terminal capacitance C_t

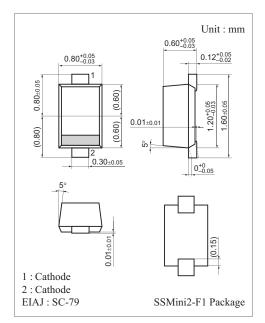
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Repetitive peak forward current	I_{FRM}	200	mA	
Total power dissipation *1	P_{T}	150	mW	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	
Electrostatic discharge *2	ESD	±15	kV	

Note) $*1: P_T = 150 \text{ mW}$ achieved with a printed circuit board.

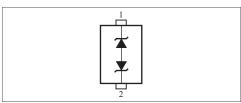
*2: Test method: IEC61000-4-2

 $(C = 150 \text{ pF}, R = 330 \Omega, \text{ Contact discharge: } 10 \text{ times})$



Marking Symbol: RX

Internal Connection



■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage *	V_Z	$I_Z = 5 \text{ mA}$	6.5	7.0	7.5	V
Zener operating resistance	R_Z	$I_Z = 5 \text{ mA}$			20	Ω
Reverse current	I_R	$V_{R^{l}} = 4.0 V$			50	nA
Terminal capacitance	C_{t}	$V_{RJ} = 0 \text{ V, } f = 1 \text{ MHz}$		15		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. The temperature must be controlled 25°C for V_Z mesurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
- 3. *: V_Z guaranted 20 ms after current flow.

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